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**Hardmetals — Metallographic  
determination of microstructure —**

**Part 2:  
Measurement of WC grain size**

*Métaux-durs — Détermination métallographique de la  
microstructure —*

*Partie 2: Mesurage de la taille des grains de WC*

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## Foreword

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The procedures used to develop this document and those intended for its further maintenance are described in the ISO/IEC Directives, Part 1. In particular, the different approval criteria needed for the different types of ISO documents should be noted. This document was drafted in accordance with the editorial rules of the ISO/IEC Directives, Part 2 (see [www.iso.org/directives](http://www.iso.org/directives)).

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This document was prepared by Technical Committee ISO/TC 119, *Powder metallurgy*, Subcommittee SC 4, *Sampling and testing methods for hardmetals*, in collaboration with the European Committee for Standardization (CEN) Technical Committee CEN/SS M11, *Powder metallurgy*, in accordance with the Agreement on technical cooperation between ISO and CEN (Vienna Agreement).

This second edition cancels and replaces the first edition (ISO 4499-2:2008), which has been technically revised.

The main changes compared to the previous edition are as follows:

- former 3.1 has been removed;
- [3.2](#) has been expanded;
- in [Clause 5](#), “Electron back scatter diffraction (EBSD)” has been added;
- in [7.2.1](#), the list has been revised;
- in [7.3.3](#), [Table 1](#), row “Electron back scatter diffraction” has been added and in the row “Scanning electron microscope”, the value for the “Minimum visible intercept length” has been corrected from 200 nm into 400 nm.

A list of all parts in the ISO 4499 series can be found on the ISO website.

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